

HD74HC4543

BCD-to-Seven Segment Latch/Decoder/Driver

REJ03D0655-0200
(Previous ADE-205-544)
Rev.2.00
Mar 30, 2006

Description

This circuit contains a 4-bit latch, BCD-to-7 segment decoder, and 7 output drivers. Data on the input pins flow through to the output when the Latch Disable (LE) is high and is latched on the high to low transition of the LE input. The Phase input (Ph) controls the polarity of the 7 segment outputs. When Ph is low the outputs are true 7 segment, and when Ph is high the outputs are inverted 7 segment. When the Phase input is driven by a liquid crystal display (LCD) backplane waveform the segment pins output the correct segment waveform for proper LCD AC drive voltages.

In addition a Blanking input (BI) is provided, which will blank the display.

Features

- High Speed Operation: t_{pd} (A, B, C, D to a – g) = 33 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)
- Ordering Information

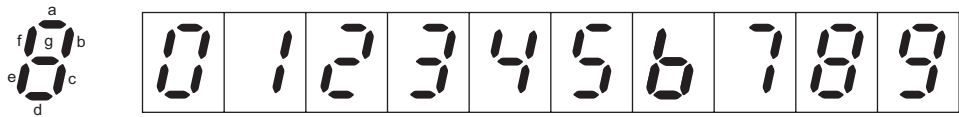
Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC4543P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74HC4543FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)
HD74HC4543RPEL	SOP-16 pin (JEDEC)	PRSP0016DG-A (FP-16DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

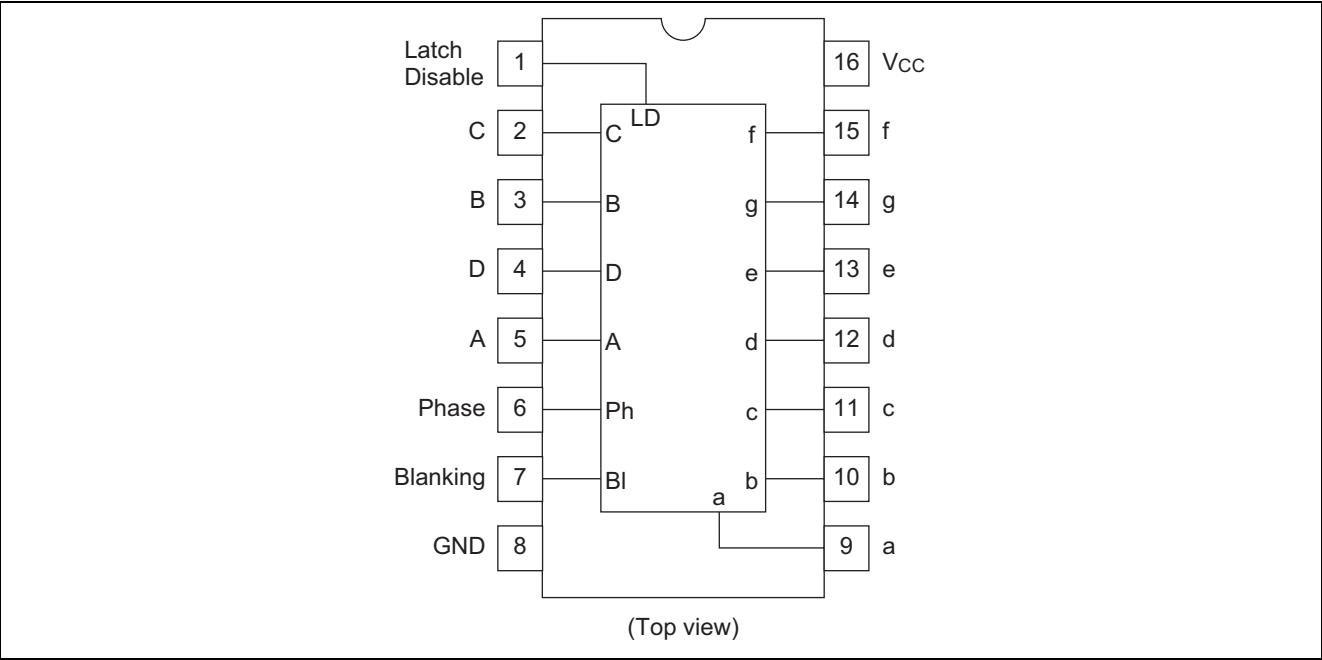
Function Table

Inputs							Outputs							
LD	BI	Ph* ¹	D	C	B	A	a	b	c	d	e	f	g	Display
X	H	L	X	X	X	X	L	L	L	L	L	L	L	Blank
H	L	L	L	L	L	L	H	H	H	H	H	H	L	0
H	L	L	L	L	L	H	L	H	H	L	L	L	L	1
H	L	L	L	L	H	L	H	H	L	H	H	L	H	2
H	L	L	L	L	H	H	H	H	H	H	L	L	H	3
H	L	L	L	H	L	L	L	H	H	L	L	H	H	4
H	L	L	L	H	L	H	H	L	H	H	L	H	H	5
H	L	L	L	H	H	L	H	L	H	H	H	H	H	6
H	L	L	L	H	H	H	H	H	H	L	L	L	L	7
H	L	L	H	L	L	L	H	H	H	H	H	H	H	8
H	L	L	H	L	L	H	H	H	H	H	L	H	H	9
H	L	L	H	L	H	L	L	L	L	L	L	L	L	Blank
H	L	L	H	L	H	H	L	L	L	L	L	L	L	Blank
H	L	L	H	H	L	L	L	L	L	L	L	L	L	Blank
H	L	L	H	H	L	H	L	L	L	L	L	L	L	Blank
H	L	L	H	H	H	L	L	L	L	L	L	L	L	Blank
H	L	L	H	H	H	H	L	L	L	L	L	L	L	Blank
L	L	L	X	X	X	X	* ²							* ¹

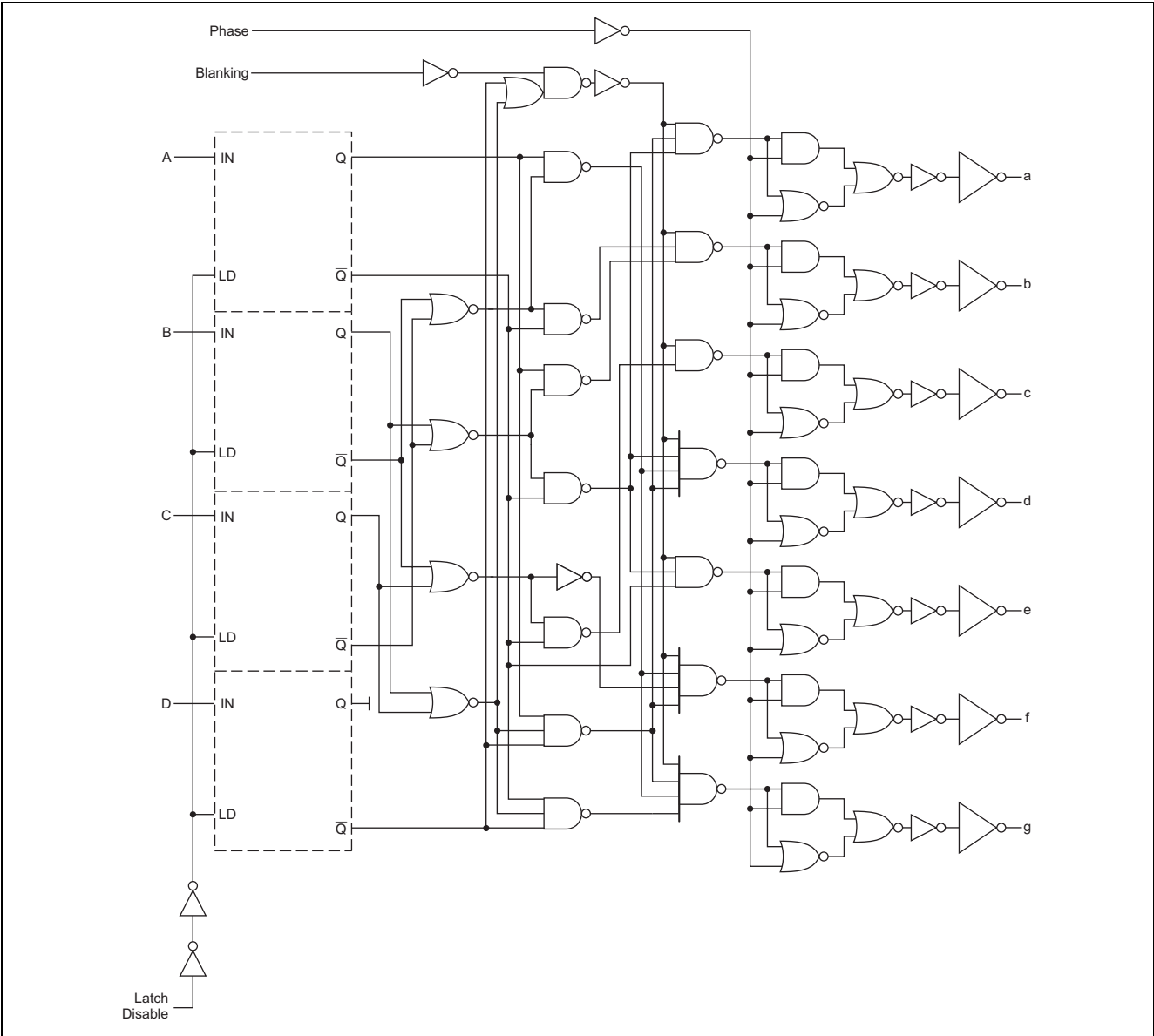
Notes: 1. For liquid crystal readouts, apply a square wave to Ph.
For common cathode LED readouts, select Ph = L. For common anode LED readouts, select Ph = H
2. Depends upon the BCD code previously applied when LD = H



Pin Arrangement



Logic Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
Input / Output voltage	V_{IN}, V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	I_{IK}, I_{OK}	± 20	mA
Output current	I_{OUT}	± 25	mA
V_{CC} , GND current	I_{CC} or I_{GND}	± 50	mA
Power dissipation	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	2 to 6	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V_{CC}	V	
Operating temperature	T_a	-40 to 85	°C	
Input rise / fall time ^{*1}	t_r, t_f	0 to 1000	ns	$V_{CC} = 2.0\text{ V}$
		0 to 500		$V_{CC} = 4.5\text{ V}$
		0 to 400		$V_{CC} = 6.0\text{ V}$

Note: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

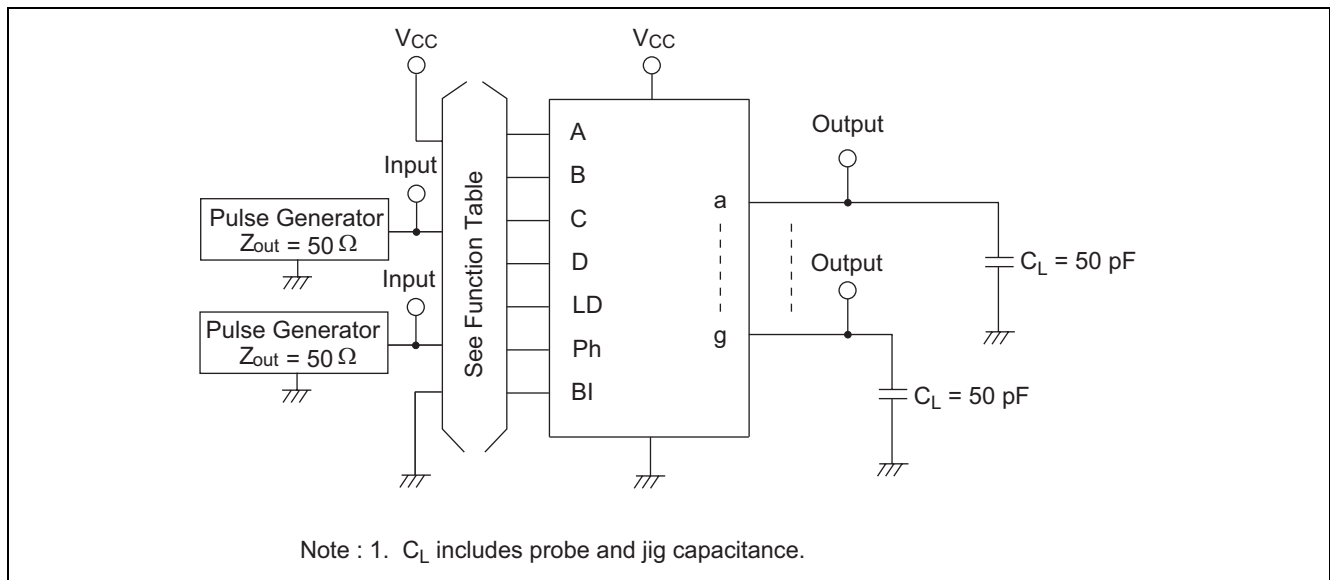
Electrical Characteristics

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40\text{ to }+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V_{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	$V_{in} = V_{IH}\text{ or }V_{IL}$	$I_{OH} = -20\text{ }\mu\text{A}$
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			$I_{OH} = -4\text{ mA}$
		6.0	5.68	—	—	5.63	—			$I_{OH} = -5.2\text{ mA}$
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	$V_{in} = V_{IH}\text{ or }V_{IL}$	$I_{OL} = 20\text{ }\mu\text{A}$
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			$I_{OH} = 4\text{ mA}$
		6.0	—	—	0.26	—	0.33			$I_{OH} = 5.2\text{ mA}$
Input current	I_{in}	6.0	—	—	± 0.1	—	± 1.0	μA	$V_{in} = V_{CC}\text{ or GND}$	
Quiescent supply current	I_{CC}	6.0	—	—	4.0	—	40	μA	$V_{in} = V_{CC}\text{ or GND, }I_{out} = 0\text{ }\mu\text{A}$	

Switching Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

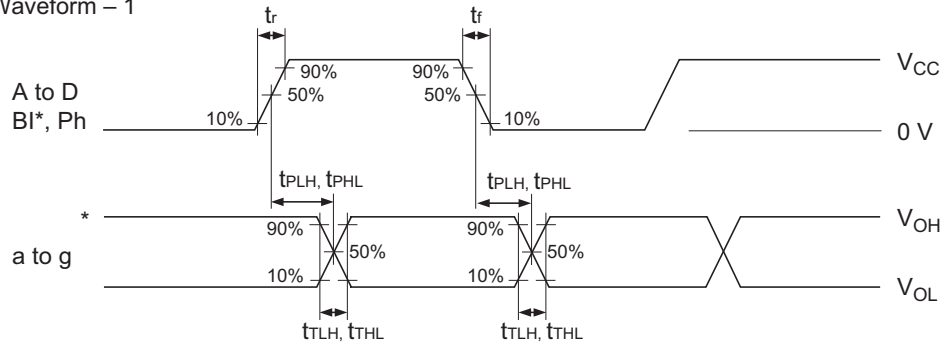
Item	Symbol	$V_{CC} \text{ (V)}$	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } +85^\circ\text{C}$		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Propagation delay time	t_{PLH}	2.0	—	—	400	—	500	ns	A, B, C or D to a – g
		4.5	—	33	80	—	100		
		6.0	—	—	68	—	86		
	t_{PHL}	2.0	—	—	300	—	380	ns	Blanking to a – g
		4.5	—	22	60	—	76		
		6.0	—	—	52	—	66		
	t_{PLH}	2.0	—	—	300	—	380	ns	Phase to a – g
		4.5	—	18	60	—	76		
		6.0	—	—	52	—	66		
Pulse width	t_w	2.0	80	—	—	100	—	ns	
		4.5	16	5	—	20	—		
		6.0	14	—	—	17	—		
Setup time	t_{su}	2.0	100	—	—	125	—	ns	
		4.5	20	2	—	25	—		
		6.0	17	—	—	21	—		
Hold time	t_h	2.0	50	—	—	65	—	ns	
		4.5	10	1	—	13	—		
		6.0	9	—	—	11	—		
Output rise/fall time	t_{TLH} t_{THL}	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

Test Circuit



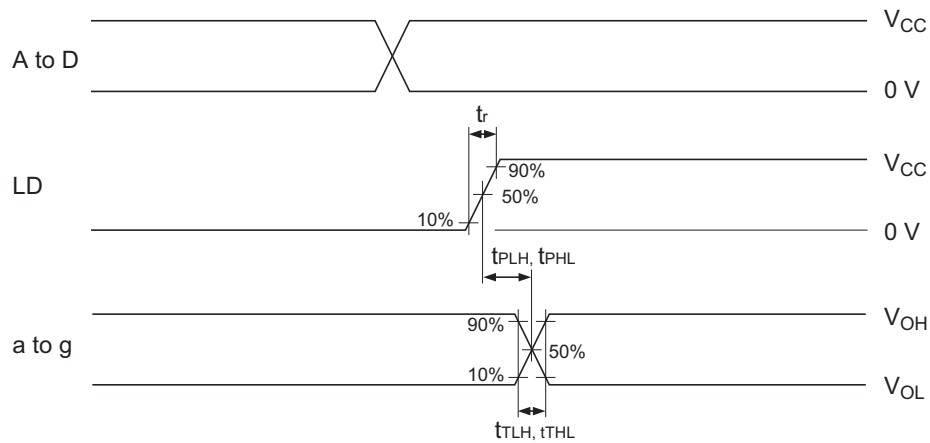
Waveforms

• Waveform – 1



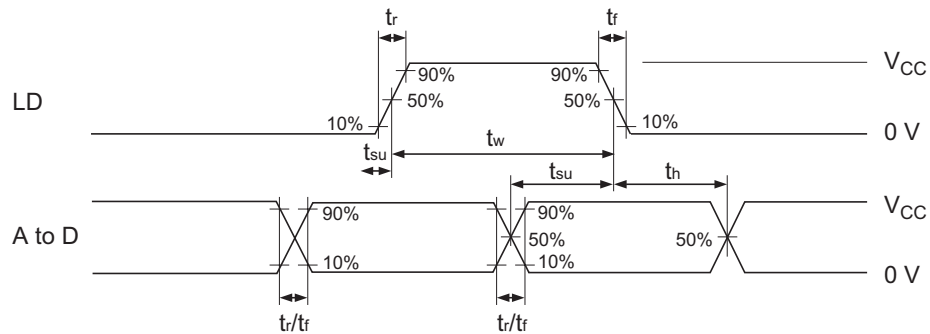
Note : 1. Input waveform: PRR $\leq$ 1 MHz, Z_o = 50 Ω , $t_r \leq$ 6 ns, $t_f \leq$ 6 ns

• Waveform – 2



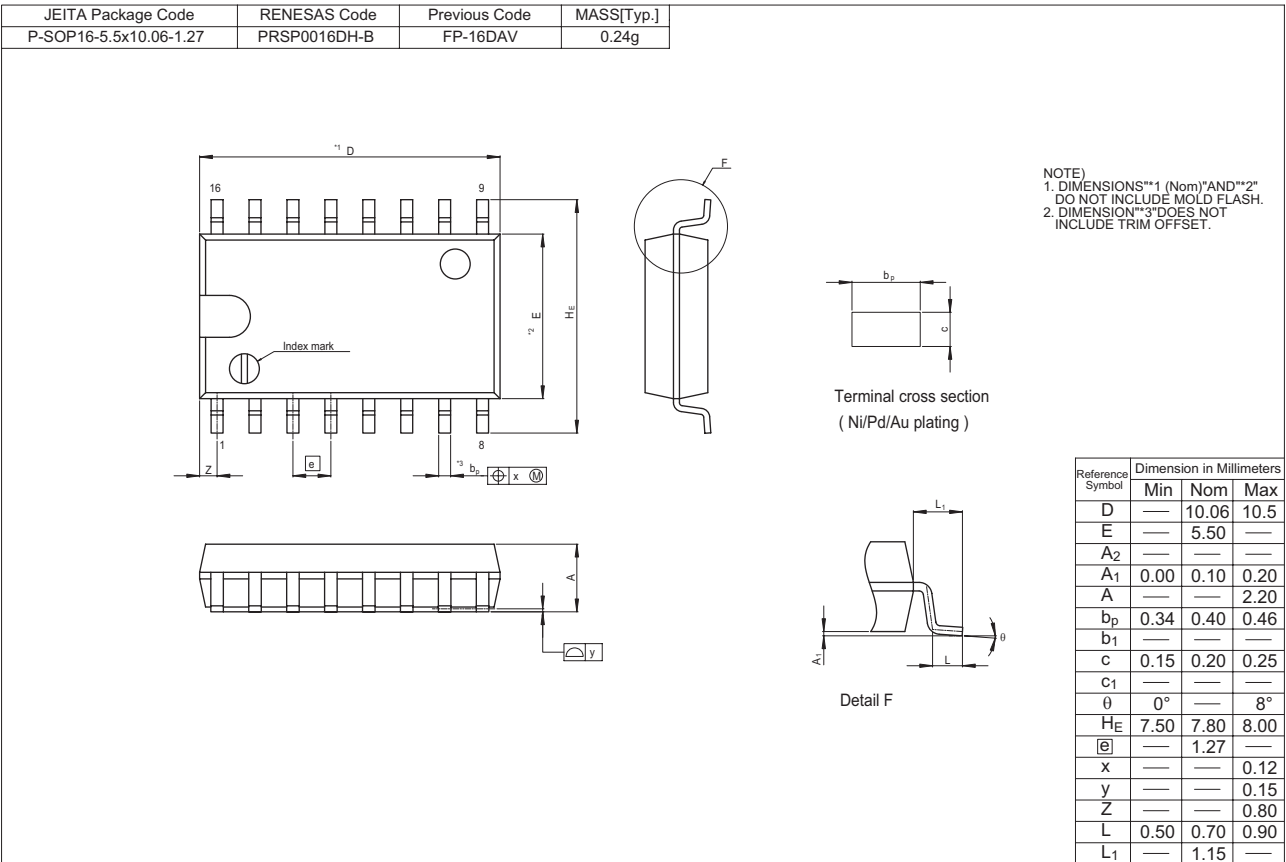
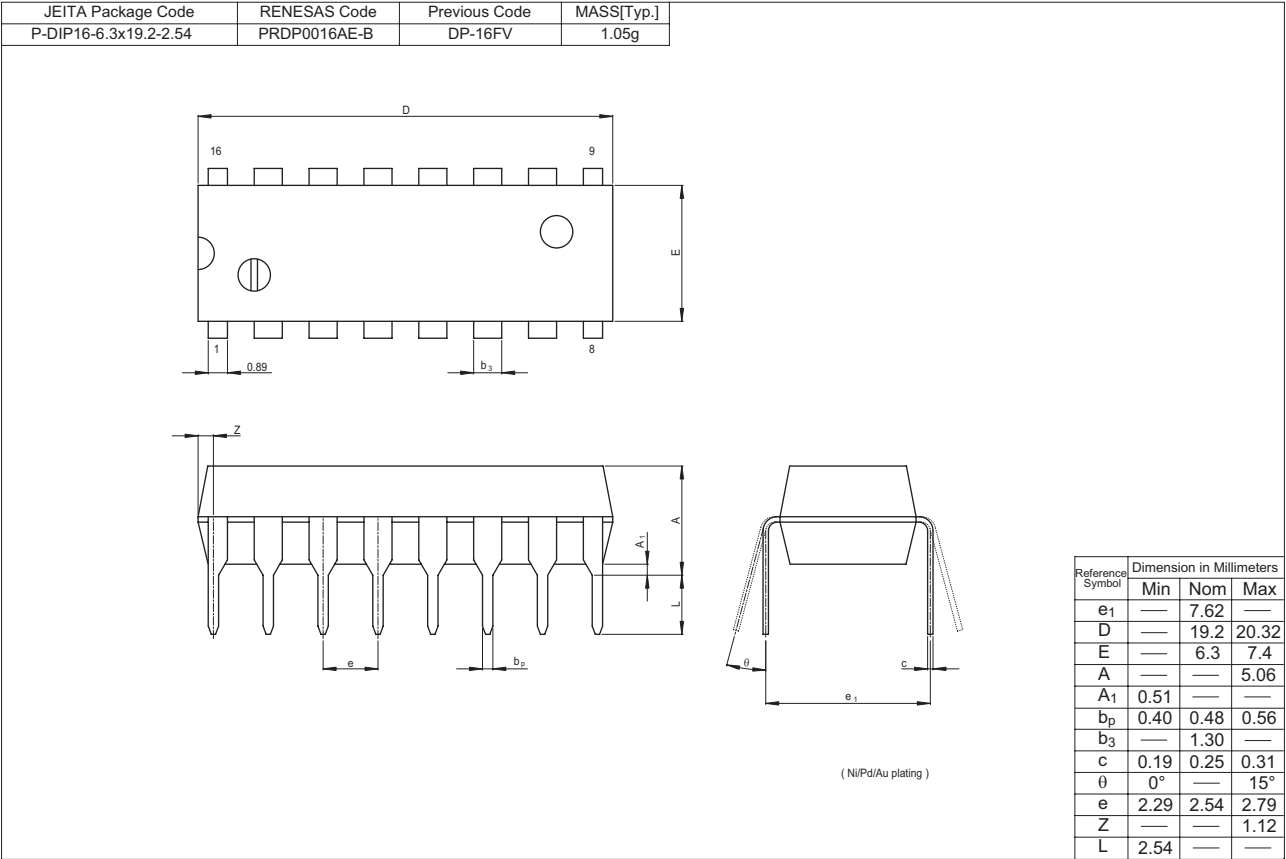
Note : 1. Input waveform: PRR $\leq$ 1 MHz, Z_o = 50 Ω , $t_r \leq$ 6 ns, $t_f \leq$ 6 ns

• Waveform – 3

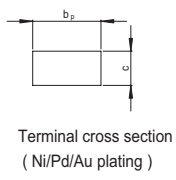
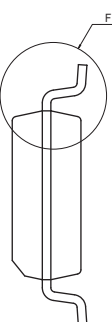
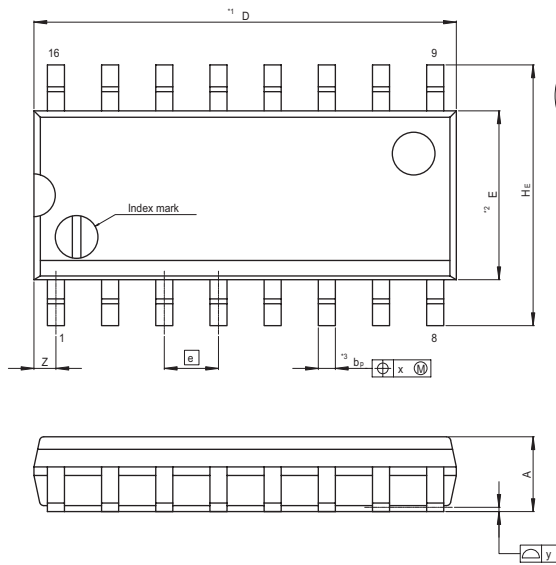


Note : 1. Input waveform: PRR $\leq$ 1 MHz, Z_o = 50 Ω , $t_r \leq$ 6 ns, $t_f \leq$ 6 ns

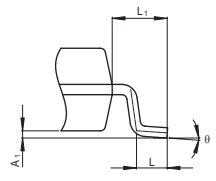
Package Dimensions



JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP16-3.95x9.9-1.27	PRSP0016DG-A	FP-16DNV	0.15g



Terminal cross section
(Ni/Pd/Au plating)



Detail F

NOTE)
1. DIMENSIONS**1 (Nom)**AND**2"
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION**3 DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	9.90	10.30
E	—	3.95	—
A ₂	—	—	—
A ₁	0.10	0.14	0.25
A	—	—	1.75
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	5.80	6.10	6.20
[e]	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L ₁	—	1.08	—

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